

EAST Search History

| Ref # | Hits | Search Query | DBs | Default Operator | Plurals | Time Stamp |
|-------|------|--|----------|------------------|---------|------------------|
| L3 | 1 | (chip and scale and package and method and comprising and providing and semiconductor and wafer and including and pads and passivation and layer and scribe and lines and between and forming and first and patterned and dielectric and exposes and second and embossed and ball and pad and convex and wiring and electrically and connected and third and removing and hole).clm. | US-PGPUB | OR | ON | 2006/11/09 21:53 |